

Product Change Notification - KSRA-04OPOO860

Date: 09 May 2017
Product Category: 16-Bit - Microcontrollers and Digital Signal Controllers
Notification subject: CCB 2938 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 0.18 TSMC wafer technology available in 28L QFN-S package at NSEB assembly site
Notification text: **PCN Status:**
 Initial notification

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 0.18 TSMC wafer technology available in 28L QFN-S package at NSEB assembly site

Pre Change:

Using gold (Au) bond wire, 8200T or 8600 die attach and G770HCD or G700LTD mold compound material.

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 8600 die attach and G700LTD mold compound material.

Pre and Post Change Summary:

	Pre Change		Post Change
Assembly Site	NSEB Assembly Site		NSEB Assembly Site
Wire material	Au Wire		CuPdAu Wire
Die attach material	8200T	8600	8600
Molding compound material	G770HCD	G700LTD	G700LTD
Lead frame material	C194		C194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying CuPdAu bond wire at NSEB assembly site.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

October 2017

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

Workweek	May 2017					-->	October 2017				
	18	19	20	21	22		40	41	42	43	44
Initial PCN Issue Date		X									
Qual Report Availability									X		
Final PCN Issue Date									X		

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan

Revision History:
May 09, 2017: Issued initial notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_KSRA-04OPOO860_Affected CPN.pdf](#)
 - [PCN_KSRA-04OPOO860_Qual Plan.pdf](#)
 - [PCN_KSRA-04OPOO860_Affected CPN.xlsx](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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KSRA-04FJDK272 -CCB 2938 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 0.18 TSMC wafer technology available in 28L QFN-S package at NSEB assembly site.

Affected Catalog Part Numbers (CPN)

PCN_KSRA-04OPOO860
CATALOG_PART_NBR
DSPIC33EP128GP502-H/MM
DSPIC33EP128GP502-I/MM
DSPIC33EP128GP502-I/MMA3
DSPIC33EP128GP502T-I/MM
DSPIC33EP128GS702-E/MM
DSPIC33EP128GS702-I/MM
DSPIC33EP128GS702T-E/MM
DSPIC33EP128GS702T-I/MM
DSPIC33EP128MC202-E/MM
DSPIC33EP128MC202-H/MM
DSPIC33EP128MC202-I/MM
DSPIC33EP128MC202-I/MMA3
DSPIC33EP128MC202T-E/MM
DSPIC33EP128MC202T-I/MM
DSPIC33EP128MC502-H/MM
DSPIC33EP128MC502-I/MM
DSPIC33EP128MC502-I/MMA3
DSPIC33EP128MC502T-E/MM
DSPIC33EP128MC502T-I/MM
DSPIC33EP16GS202-E/MM
DSPIC33EP16GS202-I/MM
DSPIC33EP16GS202T-E/MM
DSPIC33EP16GS202T-I/MM
DSPIC33EP16GS202T-I/MMC01
DSPIC33EP16GS502-E/MM
DSPIC33EP16GS502-I/MM
DSPIC33EP16GS502T-E/MM
DSPIC33EP16GS502T-I/MM
DSPIC33EP256GP502-E/MM
DSPIC33EP256GP502-H/MM
DSPIC33EP256GP502-I/MM
DSPIC33EP256GP502T-E/MM
DSPIC33EP256GP502T-H/MM
DSPIC33EP256GP502T-I/MM
DSPIC33EP256MC202-E/MM
DSPIC33EP256MC202-H/MM
DSPIC33EP256MC202-I/MM
DSPIC33EP256MC202T-E/MM
DSPIC33EP256MC202T-H/MM
DSPIC33EP256MC202T-I/MM
DSPIC33EP256MC502-E/MM
DSPIC33EP256MC502-H/MM
DSPIC33EP256MC502-I/MM

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CATALOG_PART_NBR
DSPIC33EP256MC502T-E/MM
DSPIC33EP256MC502T-H/MM
DSPIC33EP256MC502T-I/MM
DSPIC33EP32GP502-E/MM
DSPIC33EP32GP502-H/MM
DSPIC33EP32GP502-I/MM
DSPIC33EP32GP502T-E/MM
DSPIC33EP32GP502T-H/MM
DSPIC33EP32GP502T-I/MM
DSPIC33EP32GS202-E/MM
DSPIC33EP32GS202-I/MM
DSPIC33EP32GS202T-E/MM
DSPIC33EP32GS202T-I/MM
DSPIC33EP32GS202T-I/MMC02
DSPIC33EP32GS502-E/MM
DSPIC33EP32GS502-I/MM
DSPIC33EP32GS502T-E/MM
DSPIC33EP32GS502T-I/MM
DSPIC33EP32MC202-E/MM
DSPIC33EP32MC202-H/MM
DSPIC33EP32MC202-I/MM
DSPIC33EP32MC202T-E/MM
DSPIC33EP32MC202T-H/MM
DSPIC33EP32MC202T-I/MM
DSPIC33EP32MC502-E/MM
DSPIC33EP32MC502-H/MM
DSPIC33EP32MC502-I/MM
DSPIC33EP32MC502T-E/MM
DSPIC33EP32MC502T-H/MM
DSPIC33EP32MC502T-I/MM
DSPIC33EP512GP502-E/MM
DSPIC33EP512GP502-H/MM
DSPIC33EP512GP502-I/MM
DSPIC33EP512GP502T-E/MM
DSPIC33EP512GP502T-H/MM
DSPIC33EP512GP502T-I/MM
DSPIC33EP512MC202-E/MM
DSPIC33EP512MC202-H/MM
DSPIC33EP512MC202-I/MM
DSPIC33EP512MC202T-E/MM
DSPIC33EP512MC202T-H/MM
DSPIC33EP512MC202T-I/MM
DSPIC33EP512MC502-E/MM

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CATALOG_PART_NBR
DSPIC33EP512MC502-H/MM
DSPIC33EP512MC502-I/MM
DSPIC33EP512MC502T-E/MM
DSPIC33EP512MC502T-H/MM
DSPIC33EP512MC502T-I/MM
DSPIC33EP64GP502-E/MM
DSPIC33EP64GP502-H/MM
DSPIC33EP64GP502-I/MM
DSPIC33EP64GP502-I/MMA3
DSPIC33EP64GP502T-E/MM
DSPIC33EP64GP502T-H/MM
DSPIC33EP64GP502T-I/MM
DSPIC33EP64GS502-E/MM
DSPIC33EP64GS502-I/MM
DSPIC33EP64GS502T-E/MM
DSPIC33EP64GS502T-I/MM
DSPIC33EP64MC202-E/MM
DSPIC33EP64MC202-H/MM
DSPIC33EP64MC202-I/MM
DSPIC33EP64MC202T-E/MM
DSPIC33EP64MC202T-H/MM
DSPIC33EP64MC202T-I/MM
DSPIC33EP64MC502-E/MM
DSPIC33EP64MC502-H/MM
DSPIC33EP64MC502-I/MM
DSPIC33EP64MC502T-E/MM
DSPIC33EP64MC502T-H/MM
DSPIC33EP64MC502T-I/MM
DSPIC33EV128GM002-E/MM
DSPIC33EV128GM002-H/MM
DSPIC33EV128GM002-I/MM
DSPIC33EV128GM002T-I/MM
DSPIC33EV128GM102-E/MM
DSPIC33EV128GM102-H/MM
DSPIC33EV128GM102-I/MM
DSPIC33EV128GM102T-I/MM
DSPIC33EV256GM002-E/MM
DSPIC33EV256GM002-H/MM
DSPIC33EV256GM002-I/MM
DSPIC33EV256GM002T-I/MM
DSPIC33EV256GM102-E/MM
DSPIC33EV256GM102-H/MM
DSPIC33EV256GM102-I/MM

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CATALOG_PART_NBR
DSPIC33EV256GM102T-I/MM
DSPIC33EV32GM002-E/MM
DSPIC33EV32GM002-H/MM
DSPIC33EV32GM002-I/MM
DSPIC33EV32GM002T-I/MM
DSPIC33EV32GM102-E/MM
DSPIC33EV32GM102-H/MM
DSPIC33EV32GM102-I/MM
DSPIC33EV32GM102T-I/MM
DSPIC33EV64GM002-E/MM
DSPIC33EV64GM002-H/MM
DSPIC33EV64GM002-I/MM
DSPIC33EV64GM002T-I/MM
DSPIC33EV64GM102-E/MM
DSPIC33EV64GM102-H/MM
DSPIC33EV64GM102-I/MM
DSPIC33EV64GM102T-I/MM
PIC24EP128GP202-E/MM
PIC24EP128GP202-H/MM
PIC24EP128GP202-I/MM
PIC24EP128GP202-I/MMA3
PIC24EP128GP202T-I/MM
PIC24EP128GP202T-I/MM020
PIC24EP128MC202-H/MM
PIC24EP128MC202-I/MM
PIC24EP128MC202-I/MMA3
PIC24EP128MC202T-I/MM
PIC24EP256GP202-E/MM
PIC24EP256GP202-H/MM
PIC24EP256GP202-I/MM
PIC24EP256GP202T-E/MM
PIC24EP256GP202T-H/MM
PIC24EP256GP202T-I/MM
PIC24EP256MC202-E/MM
PIC24EP256MC202-H/MM
PIC24EP256MC202-I/MM
PIC24EP256MC202T-E/MM
PIC24EP256MC202T-H/MM
PIC24EP256MC202T-I/MM
PIC24EP32GP202-E/MM
PIC24EP32GP202-H/MM
PIC24EP32GP202-I/MM
PIC24EP32GP202T-E/MM

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PIC24EP32GP202T-H/MM
PIC24EP32GP202T-I/MM
PIC24EP32MC202-E/MM
PIC24EP32MC202-H/MM
PIC24EP32MC202-I/MM
PIC24EP32MC202T-E/MM
PIC24EP32MC202T-H/MM
PIC24EP32MC202T-I/MM
PIC24EP512GP202-E/MM
PIC24EP512GP202-H/MM
PIC24EP512GP202-I/MM
PIC24EP512GP202T-E/MM
PIC24EP512GP202T-H/MM
PIC24EP512GP202T-I/MM
PIC24EP512MC202-E/MM
PIC24EP512MC202-H/MM
PIC24EP512MC202-I/MM
PIC24EP512MC202T-E/MM
PIC24EP512MC202T-H/MM
PIC24EP512MC202T-I/MM
PIC24EP64GP202-E/MM
PIC24EP64GP202-H/MM
PIC24EP64GP202-I/MM
PIC24EP64GP202-I/MMA3
PIC24EP64GP202T-E/MM
PIC24EP64GP202T-H/MM
PIC24EP64GP202T-I/MM
PIC24EP64MC202-E/MM
PIC24EP64MC202-H/MM
PIC24EP64MC202-I/MM
PIC24EP64MC202T-E/MM
PIC24EP64MC202T-H/MM
PIC24EP64MC202T-I/MM
PIC24FJ128GA202-E/MM
PIC24FJ128GA202-I/MM
PIC24FJ128GA202T-I/MM
PIC24FJ128GB202-E/MM
PIC24FJ128GB202-I/MM
PIC24FJ128GB202T-I/MM
PIC24FJ64GA202-E/MM
PIC24FJ64GA202-I/MM
PIC24FJ64GA202T-I/MM
PIC24FJ64GB202-E/MM

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PIC24FJ64GB202-I/MM
PIC24FJ64GB202T-I/MM